

# The latest in thermally conductive adhesives

New developments and applications in energy and electrical engineering can require ever higher levels of thermal conductivity – hence our partners **Polytec PT** are developing the next generation of [thermally conductive two-part epoxy adhesives](#).

These new high performance adhesives offer excellent thermal conductivity, so enhancing the effectiveness of heat paths found in applications such as LED heat sink attachment, chip assembly, encapsulation, potting of thermal sensors, assembly of power modules, connection of pipes in heat exchangers and the bonding and potting of battery cells and electric motors. They can help optimise production processes with a choice of accelerated thermal cures in about 15 minutes or 24 hours at room temperature.

A good example is [Polytec TC 433](#), an advanced semi-rigid boron nitride filled adhesive. It features 2 W/m·K thermal conductivity and a glass transition around 110°C after thermal curing, withstanding up to 220°C continuous operation temperature.

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